AM/DM37x Multimedia Device
Silicon Revision 1.x
Texas Instruments OMAP™ Family of Products

Delta between version Q and version R

Literature Number: SPRUGW9Q
September 12
WARNING: EXPORT NOTICE

Recipient agrees to not knowingly export or re-export, directly or indirectly, any product or technical data (as defined by the U.S., EU and other Export Administration Regulations) including software, or any controlled product restricted by other applicable national regulations, received from Disclosing party under this Agreement, or any direct product of such technology, to any destination to which such export or re-export is restricted or prohibited by U.S. or other applicable laws, without obtaining prior authorization from U.S. Department of Commerce and other competent Government authorities to the extent required by those laws. This provision shall survive termination or expiration of this Agreement.

According to our best knowledge of the state and end-use of this product or technology, and in compliance with the export control regulations of dual-use goods in force in the origin and exporting countries, this technology is classified as follows:

- US ECCN: 3E991
- EU ECCN: EAR99

and may require export or re-export license for shipping it in compliance with the applicable regulations of certain countries.
Table of Contents

WARNING: EXPORT NOTICE ................................................................................................ ii
Table of Contents .................................................................................................................. iii
AM/DM37x ES1.x TRM Delta introduction ........................................................................... 5
Preface .................................................................................................................................. 6
Chapter 1: Introduction ........................................................................................................ 6
Chapter 2: Memory Mapping ............................................................................................... 6
Chapter 3: Power, Reset, and Clock Management .............................................................. 6
Chapter 4: MPU Subsystem ............................................................................................... 6
Chapter 5: IVA2.2 Subsystem ........................................................................................... 6
Chapter 6: Camera Image Signal Processor ....................................................................... 6
Chapter 7: Display Subsystem ........................................................................................... 7
  7.1 ProDB00114644: HDMI support through DSI interface ............................................. 7
Chapter 8: 2D/3D Graphics Accelerator ............................................................................ 8
Chapter 9: Interconnect ..................................................................................................... 8
Chapter 10: Memory Subsystem ....................................................................................... 8
Chapter 11: SDMA .............................................................................................................. 8
Chapter 12: Interrupt Controller ........................................................................................ 8
Chapter 13: System Control Module ................................................................................ 8
Chapter 14: Interprocessor Communication ..................................................................... 8
Chapter 15: Memory Management Units ......................................................................... 8
Chapter 16: Timers ............................................................................................................. 8
Chapter 17: I²C ..................................................................................................................... 8
Chapter 18: HDQ/1-Wire ................................................................................................. 9
Chapter 19: UART/IrDA/CIR .......................................................................................... 10
  19.1 ProDB00121218: THR_REG register is limited to 8-bit data access ...................... 10
Chapter 21: Multichannel Buffered Serial Port ............................................................... 11
Chapter 22: High-Speed USB Host Subsystem and High-Speed USB OTG Controller. 11
Chapter 23: Memory Stick PRO Host Controller ............................................................ 11
Chapter 24: MMC/SD/SDIO Card Interface .................................................................... 11
Chapter 25: General-Purpose Interface ......................................................................... 11
Chapter 26: Initialization ................................................................................................. 11
Chapter 27: Debug and Emulation .................................................................................. 11
A: Glossary ........................................................................................................................................11
AM/DM37x ES1.x TRM Delta introduction

This document contains all the differences between AM/DM37x_ES1.x_TRM_vQ (literature number SPRUGN4Q) and AM/DM37x_ES1.x_TRM_vR (literature number SPRUGN4R).

Reading rules:

Strike through = removed.
Highlighted in yellow = added or updated

Tables and Figures refer to the previous TRM version. In the new TRM version; their numbering may change due to additional or removal of Tables or Figures.
Preface
No difference.

Chapter 1: Introduction
No difference.

Chapter 2: Memory Mapping
No difference.

Chapter 3: Power, Reset, and Clock Management
No difference.

Chapter 4: MPU Subsystem
No difference.

Chapter 5: IVA2.2 Subsystem
No difference.

Chapter 6: Camera Image Signal Processor
No difference.
Chapter 7: Display Subsystem

7.1 ProDB00114644: HDMI support through DSI interface

DESCRIPTION
The maximum resolution supported on DSI video port need to be aligned with actual implementation.

CORRECTION
The following modifications are applied:

7.1 Display Subsystem Overview

- MIPI DSI
  - Transfer pixels and data received on the video port or L4 interconnect to the display through the DSI DSI_PHY
  - The maximum resolution supported on the video port is XGA SVGA at 60 fps with 24-bit pixels (maximum pixel clock of 67.48 MHz) for low voltage, and WXGA at 60 fps with 24-bit pixels (maximum pixel clock of 86.5 MHz) for nominal voltage
  - Supports video mode and command mode
Chapter 8: 2D/3D Graphics Accelerator
No difference.

Chapter 9: Interconnect
No difference.

Chapter 10: Memory Subsystem
No difference.

Chapter 11: SDMA
No difference.

Chapter 12: Interrupt Controller
No difference.

Chapter 13: System Control Module
No difference.

Chapter 14: Interprocessor Communication
No difference.

Chapter 15: Memory Management Units
No difference.

Chapter 16: Timers
No difference.

Chapter 17: I²C
No difference.
Chapter 18: HDQ/1-Wire

No difference.
Chapter 19: UART/IrDA/CIR

19.1 ProDB00121218: THR_REG register is limited to 8-bit data access

DESCRIPTION

THR_REG register is limited to 8-bit data access.

CORRECTION

A note that THR_REG register is limited to 8-bit data access is added to Table 19-45. THR_REG register and typo update.

19.6.1 UART/IrDA/CIR Instance Summary

**CAUTION**

The UART_THR register is limited to 8-bit data accesses; 16- and 32-bit data accesses are not allowed and can corrupt the register content. Only 8-bit and 16-bit accesses are allowed for the THR_REG register. Performing a 32-bit access can result in a data abort.

<table>
<thead>
<tr>
<th>Address Offset</th>
<th>Physical Address</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>0x000</td>
<td>See Table 19-39 to Table 19-40</td>
<td>Transmit holding register The transmitter section consists of the transmit holding register (THR_REG) and the transmit shift register. The transmit holding register is a 64-byte FIFO. The MPU writes data to the THR_REG. The data is placed in the transmit shift register where it is shifted out serially on the TX output. If the FIFO is disabled, location zero of the FIFO is used to store the data. Note: Only 8-bit and 16-bit accesses are allowed for the THR_REG register. Performing a 32-bit access can result in a data abort.</td>
</tr>
</tbody>
</table>

| Type | W |


Chapter 20: Multichannel SPI
No difference.

Chapter 21: Multichannel Buffered Serial Port
No difference.

Chapter 22: High-Speed USB Host Subsystem and High-Speed USB OTG Controller
No difference.

Chapter 23: Memory Stick PRO Host Controller
No difference.

Chapter 24: MMC/SD/SDIO Card Interface
No difference.

Chapter 25: General-Purpose Interface
No difference.

Chapter 26: Initialization
No difference.

Chapter 27: Debug and Emulation
No difference.

A: Glossary
No difference.
IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party, independent of TI.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

TI products are neither designed nor intended for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify and hold TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<table>
<thead>
<tr>
<th>Products</th>
<th>Applications</th>
</tr>
</thead>
<tbody>
<tr>
<td>Audio</td>
<td>Communications &amp; Telecom</td>
</tr>
<tr>
<td>Amplifiers</td>
<td>Computers &amp; Peripherals</td>
</tr>
<tr>
<td>Data Converters</td>
<td>Consumer Electronics</td>
</tr>
<tr>
<td>DLP® Products</td>
<td>Energy and Lighting</td>
</tr>
<tr>
<td>DSP</td>
<td>Industrial</td>
</tr>
<tr>
<td>Clocks and Timers</td>
<td>Medical</td>
</tr>
<tr>
<td>Interface</td>
<td>Security</td>
</tr>
<tr>
<td>Logic</td>
<td>Space, Avionics &amp; Defense</td>
</tr>
<tr>
<td>defense</td>
<td></td>
</tr>
<tr>
<td>Power Mgmt</td>
<td>Transportation &amp; Automotive</td>
</tr>
<tr>
<td>Microcontrollers</td>
<td>Video &amp; Imaging</td>
</tr>
<tr>
<td>RFID</td>
<td>Wireless</td>
</tr>
<tr>
<td>RF/IF and ZigBee® Solutions</td>
<td></td>
</tr>
</tbody>
</table>

 TI E2E Community Home Page  e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright 2012, Texas Instruments Incorporated
IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice.

TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer’s risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio www.ti.com/audio
Amplifiers amplifier.ti.com
Data Converters dataconverter.ti.com
DLP® Products www.dlp.com
DSP dsp.ti.com
Clocks and Timers www.ti.com/clocks
Interface interface.ti.com
Logic logic.ti.com
Power Mgmt power.ti.com
Microcontrollers microcontroller.ti.com
RFID www.ti-rfid.com
OMAP Applications Processors www.ti.com/omap
Wireless Connectivity www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation www.ti.com/automotive
Communications and Telecom www.ti.com/communications
Computers and Peripherals www.ti.com/computers
Consumer Electronics www.ti.com/consumer-apps
Energy and Lighting www.ti.com/energy
Industrial www.ti.com/industrial
Medical www.ti.com/medical
Security www.ti.com/security
Space, Avionics and Defense www.ti.com/space-avionics-defense
Video and Imaging www.ti.com/video

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2012, Texas Instruments Incorporated